

NXP SEMICONDUCTORS, MICROCONTROLLER DIVISION
CUSTOMER ERRATA AND INFORMATION SHEET

Part: MPC561.D

General Business Use

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AR_910 USIU: PITRTC Clock may not work when SCCR[RTDIV] is 0
AR_1134 USIU: RTC, DEC, TB and PIT counters may not count after PORESET or HRESET
AR_1158 USIU: Stop Time Base to write new value
AR_287 USIU: System to Time Base frequency ratio must be greater than 4
AR_479 USIU: The MEMC does not support external master burst cycles
AR_1135 USIU: Disable USIU burst in debug mode if READI R/W feature is used
AR_1152 USIU: PORESET must always be asserted before the 2.6V supplies reach 0.5V
AR_867 USIU: Do not operate USIU burst on a burst-inhibited memory region

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AR_1154 SIU: RTSEC register not documented; May affect the initial increment of the RTC
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AR_1109 USIU: Do not write zero value to the SYPCR[BMT]
AR_1120 USIU: Interrupt Controller may generate vector 0x0 or has no request indication
AR_1137 USIU: RSR[LLRS] can be set even though no loss of lock reset has occurred
AR_1155 SIU: TEA for external access must be negated within 1 system bus clock

DETAILED ERRATA DESCRIPTIONS

CDR_AR_916	Customer Information	MPC561.D
Shunt Regulator: VDDSRAM pin renamed IRAMSTBY		

DESCRIPTION:

The VDDSRAM pin has been renamed IRAMSTBY to clarify that it requires a current source and should not be connected directly to a power supply.

WORKAROUND:

Consult the MPC561/MPC563 Reference Manual dated after May 2003. Rename the VDDSRAM pin to IRAMSTBY.

CDR_AR_954	Customer Information	MPC561.D
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Shunt Regulator: Max average current into IRAMSTBY (VDDSRAM) must be < 1.75 mA

DESCRIPTION:

Changes have been made to MPC563.A and MPC561.C to increase the maximum average IRAMSTBY current to 1.75 mA.

WORKAROUND:

Size the resistor between the supply and the IRAMSTBY pin (was VDDSRAM) to limit the maximum average current to 1.75 mA into the pin. Refer to manual dated on or after May 2003.

CDR_AR_978	Customer Information	MPC561.D
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USIU: Don't Enable Internal Non-Existent Flash

DESCRIPTION:

If the internal flash memory region is enabled (by setting IMMR[FLEN] = 1) on the MPC561, access to that region will result in an exception causing failure of the application code.

WORKAROUND:

Never set the FLEN bit in the IMMR or in the external Reset Configuration Word for the MPC561. Refer to manual dated on or after May 2003.

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CDR_AR_1034 Customer Information MPC561.D

Shunt Regulator: ZOREG may be set if minimum current is less than 150uA

DESCRIPTION:

Memories supplied by the IRAMSTBY pin only require a minimum of 50uA to guarantee data retention, but the VSRMCR[ZOREG] may get set inadvertently at currents less than 150uA. When designing a system where the minimum current on the IDDSRAM pin can fall below 150uA, the VSRMCR[ZOREG] bit might be set.

WORKAROUND:

Either insure that IRAMSTBY is supplied with at least 150uA when designing the system, or software should expect that the VSRMCR[ZOREG] bit might be set and take the necessary precautions that the memory contents may or may not be corrupted. Refer to manual dated on or after May 2003.

CDR_AR_1095 Customer Information MPC561.D

MPC561: Part marking is Rev D

DESCRIPTION:

On devices that no longer show the Mask Set in the part marking, the part marking may show the part Revision, for example, Rev D. Note: During this part marking change from Mask Set to Revision, some parts may be marked with a D as the part suffix (i.e. MPC561MZP56D - 56 MHz).

WORKAROUND:

If the part marking does not indicate the revision, read the Mask Number field of the Internal Memory Map Register (IMMR[MASKNUM]) to determine the revision of the MPC561.

CDR_AR_1108 Customer Information MPC561.D

TPUROM: ID is now 0x3

DESCRIPTION:

A new function containing several sub-functions has been added to the TPUROM utilizing the previously unused function 7 in bank 1. The new sub-functions include: the running average of speed, a PWM analyzer, and a 32-bit free running counter that can be either incrementing or decrementing.

WORKAROUND:

Read the version of the TPUROM using the ID function before using the new function. Refer to updated documentation on the use of these new functions. Note this version of the TPU is 0x3 and also contains the corrected COMM function (See AN_1082).

CDR_AR_1110 Customer Information MPC561.D

REV field in the READI is 0x3

DESCRIPTION:

The REV field of the READI Device Identification (DID) register has been changed to 0x3 and may change for future revisions.

WORKAROUND:

Modify software to expect a new value (0x3) for the REV field of the READI DID.

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CDR_AR_1111	Customer Information	MPC561.D
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MASKNUM field in the USIU is 0x30

DESCRIPTION:

The MASKNUM field of the IMMR register has been changed to 0x30 and may change for future revisions.

WORKAROUND:

Modify software to expect a new value (0x30) for the MASKNUM field of the IMMR.

CDR_AR_1140	Customer Information	MPC561.D
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USIU: BR0 Fields are not cleared by any Reset

DESCRIPTION:

The Reset state of Chip Select Base Register 0 (BR0) in the September 2003 (09/2003) MPC561/563 Reference Manual is incorrect. The Base Address (BA) and Address Type (AT) fields are undefined after PORESET and are unchanged by HRESET.

WORKAROUND:

BR0 should always be written to a known state prior to writing the Option Register 0 that clears the Global Chip Select mode.

CDR_AR_904	Customer Erratum	BBC2.2K_CDR3UBUS_09_0
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BBC2: Branch targets must be 4 sequential instructions before MTSR BBC SPR.

DESCRIPTION:

A user application may crash when a BBC SPR is written in a program loop, if the MTSR is within 4 instructions of a branch target.

WORKAROUND:

1) Make sure that a "mtspr" instruction writing to any BBC SPR register is preceded by four instructions that are not the target of any branch and followed by "isync" instruction, or 2) Disable BTB. Refer to manual dated on or after May 2003.

CDR_AR_870	Customer Erratum	BBC2.2K_CDR3UBUS_09_0
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BBC2: Do not use debug mode with BTB enabled, if code has 0x2F30 branch target.

DESCRIPTION:

The BTB (Branch Target Buffer) incorrectly matches in debug mode if there was a change of flow address of 0x2F30 and code from the address resides in the valid BTB buffer when the part enters debug mode. The address 0x2F30 is the debug port instruction register (SPR) address that the core issues to the BBC in debug mode for instruction fetches. The debug tool may lose communication with the part since the debug port will not assert the "ready" status (DSDO pin "low") until reset.

WORKAROUND:

Do not use debug mode on applications running with the BTB enabled if there is a branch with a target address of 0x2F30. Alternatively, either do not enable the BTB in debug mode or do not put any code at 0x2F30.

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CDR_AR_1079 Customer Erratum BBC2.2K_CDR3UBUS_09_0

BBC2: Flush the BTB if instructions in a region are changed during execution

DESCRIPTION:

If an IMPU region register has the BTB inhibit bit set ($MI_RAx[BTBINH] = 1$), the BTB inhibit function does not work for the first branch pointing into the region. These instructions will be stored in a vacant BTB table entry. Any following branches in the same region will NOT be stored in the BTB. This is the correct operation. In addition, the instructions following a branch out of the region will not be stored in the BTB table. This issue will only cause problems if there is a possibility that the instructions at a cached address are changed after they have been executed once.

WORKAROUND:

1) Disable the BTB if the caching from a memory region is undesirable; or 2) Flush the BTB by disabling and then re-enabling the BBCMCR[BTEE] any time the contents of a memory changes, prior to executing from that memory.

CDR_AR_1121 Customer Erratum BBC2.2K_CDR3UBUS_09_0

BBC2: Do not run software from the DECRAM that modifies the DECRAM contents

DESCRIPTION:

When executing code from the DECRAM, a store instruction with destination address in the DECRAM may result in an overwrite of that code area.

WORKAROUND:

Do not perform data writes to the DECRAM while also executing code from DECRAM. The DECRAM should only be loaded while executing from a different memory.

CDR_AR_793 Customer Information BBC2.2K_CDR3UBUS_09_0

BBC2 Compression: No Compressed Code in Addresses \$FFF00000 to \$FFFFFFFF

DESCRIPTION:

IMPU translates addresses in compression mode regardless of address form. Note that this may have a minor application impact. It will cause a failure ONLY if the compressed address space covers \$FFF00000 to \$FFFFFFFF and the BBCMCR[ETRE] and BBCMCR[EIR] are set, enabling Exception Table Relocation and Enhanced External Interrupt Relocation.

WORKAROUND:

Do not put compressed code at addresses \$FFF00000 to \$FFFFFFFF if Exception Table Relocation or Enhanced External Interrupt Relocation are enabled by BBCMCR[ETRE] and BBCMCR[EIR]. Refer to manual dated on or after May 2003.

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CDR_AR_1143 Customer Information L2U.CDR3LBUSUBUS_03_0

L2U: Care required when changing a slave MCU's mode in multi-master system.

DESCRIPTION:

If an external master changes the mode of a slave MCU from slave to peripheral mode by setting EMCR[PRPM], and then accesses addresses on the slave MCU's LBUS at the same time as the slave MCU's RCPU accesses addresses over the UBUS for data, a deadlock may occur. The slave MCU may lock up until reset assertion.

WORKAROUND:

Ensure the slave MCU's RCPU does not perform data accesses over the UBUS when an external master changes the slaves MCU mode from slave to peripheral mode, and then accesses the slave MCU's LBUS (i.e. CALRAM). Use interrupts or other notification mechanisms to prevent the slave MCU's RCPU from writing/reading data over UBUS. If the slave MCU changes its own mode, ensure any subsequent load/store instruction over the UBUS is at least 6 instructions after the write to EMCR[PRPM], or that they are separated by an ISYNC instruction.

CDR_AR_929 Customer Erratum MIOS14.CDR3IMB3_03_0A

MIOS: Problem with DASM Duty Cycle Change to 0%

DESCRIPTION:

If the MIOS DASM is used for a OPWM function, a problem occurs if the duty cycle is changed to 0%. The module finishes the current cycle and then it generates one period with 100% duty cycle before it switches to 0% duty cycle.

WORKAROUND:

There are three cases required for the workaround (case 3 has two different solutions):
1.) When changing from a duty cycle >0% to a different duty cycle >0%, change the dataB register to the new value.
2.) When changing from a duty cycle >0% to a duty cycle of 0%, change the dataA register to equal the value currently in the dataB register.
3a.) When changing from a duty cycle of 0% to a duty cycle >0%, change the dataA register and dataB register by doing a 32-bit write that writes both registers to new values.
OR 3b.) When changing from a duty cycle of 0% to a duty cycle >0%, write the dataA register to a value that will never match, then write the dataB register to its new value, then write the dataA register to its new value. An alternative implementation of 0% or 100% duty cycle can be achieved using the FORCE bits. For 0% duty cycle (100% if EDPOL=1), stop the associated MMCSM counter by writing 00 to the MMCSMSCR CLS bits, then write the MDASM FORCE bit to 1. For 100% duty cycle (0% if EDPOL=1), stop the associated MMCSM counter by writing 00 to the MMCSMSCR CLS bits, then write the MDASM FORCA bit to 1.

CDR_AR_1127 Customer Information MIOS14.CDR3IMB3_03_0A

MIOS: MDASMSCR polarity bit has no effect when open-drain mode selected

DESCRIPTION:

MDASMSCR[EDPOL] does not change the polarity of the MDA pin when MDASMSCR[WOR] = 1. This only applies to the MDASM output modes (OCB, OCAB and OPWM).

WORKAROUND:

Do not rely on MDASMSCR[EDPOL] to change the output polarity when open-drain mode is selected for an MDASM pin in output mode. Refer to the latest version of the Reference Manual (dated August 2003 or later).

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CDR_AR_1128 Customer Information PADRING.561_CDR3_04_0

PADS: Pull device is always enabled on BR, BB, DSDI, DSCK, TMS, JCOMP and TEXP

DESCRIPTION:

If PDMCR[SPRDS] is set by software after reset negates, the weak internal pull device on the following pads remains enabled: VF1/IWP2/BR, VF2/IWP3/BB, TDI/DSDI/MDIO, TCK/DSCK/MCKI, TMS/EVTI, JCOMP/RSTI and RSTCONF/TEXP. This has no impact on applications designed according to the specification.

WORKAROUND:

There is no workaround required for applications designed according to the specification. If PDMCR[SPRDS] is set, and the pin is set to input mode, the existing external pull device or driver will overdrive the weak internal pull device (maximum = 130uA) on the following pads: VF1/IWP2/BR, VF2/IWP3/BB, TDI/DSDI/MDIO, TCK/DSCK/MCKI, TMS/EVTI, JCOMP/RSTI and RSTCONF/TEXP.

CDR_AR_922 Customer Information PADRING.561_CDR3_04_0

PADS: VOH2.6 Spec changed to -1 mA

DESCRIPTION:

The IOH specification for all 2.6 volt outputs has been changed from -2 mA to -1 mA to insure a VOH2.6 of 2.3 volts. An additional specification has been added for VOH2.6A for a -2.0 mA load with a minimum VOH of 2.1 volts.

WORKAROUND:

2.6 volt outputs will only drive -1.0 mA with a VOH of 2.3 volts and will drive 2.0 mA with an output voltage of 2.1 volts minimum. Refer to manual dated after June 2001.

CDR_AR_932 Customer Information PADRING.561_CDR3_04_0

PADS: Leakage higher when 2.6V pads are pulled above 2.6V supply during reset

DESCRIPTION:

2.6V and 2.6V/5V pads will leak up to 10uA during reset. The leakage will occur to the QVDDL supply from each 2.6V pad which has a voltage greater than QVDDL. This additional leakage does not occur on 5V only pads.

WORKAROUND:

Cumulative input leakage of all pins pulled above the 2.6V supply must be utilized by loads on the 2.6V supply during low power modes while reset is applied. Refer to manual dated on or after May 2003.

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CDR_AR_940 Customer Information PADRING.561_CDR3_04_0
JTAG: Do Not Switch All Pads Simultaneously When JTAG Enabled

DESCRIPTION:

JTAG mode puts all output pins in fast slew rate mode. The power supply pins of the device cannot supply enough current to allow all pins to be changed at the same time in fast slew rate mode. During normal operation, this is not an issue since all pins on the device do not switch at the same time.

WORKAROUND:

When using JTAG, all pins should not be switched simultaneously. Refer to manual dated on or after May 2003.

CDR_AR_966 Customer Information PADRING.561_CDR3_04_0

USIU: MODCK[1] Reset State is Pull Up to 2.6v

DESCRIPTION:

The 29 June 2001 MPC561/MPC563 Reference Manual lists the default reset value of the MODCK[1] as Pull Down until reset negates. It is actually Pull Up to 2.6 volts until reset negates.

WORKAROUND:

Put an external pull down resistor on MODCK[1] if a 0 value is needed at reset to configure the default clock mode. The Reference Manual will be updated, see manual dated after November 2002.

CDR_AR_1018 Customer Information PADRING.561_CDR3_04_0

Execute memory write prior to slave read for slave precharge

DESCRIPTION:

When using multiple processors on a common bus with an external device that outputs voltages exceeding 3.1v, the precharge cycle will not occur if the processor that initiated the read is different than the processor that initiated the write.

WORKAROUND:

Perform a write access to external memory to discharge the external bus, or read a value of 0x0 from the external device prior to accessing another MPC56x device on the same bus. Refer to manual dated on or after May 2003.

CDR_AR_837 Customer Information PPM.CDR3_IMB3_02_0

PPM: Shorting TPU3 channels via PPM will not drive the data on the input pin.

DESCRIPTION:

If TPU3B ch[0] direction is set to output and TPU3A ch[0] direction is set to input, then TPU3A channel will get the data from TPU3B ch[0], the TPU3B ch[0] pad will show the data, but TPU3A ch[0] pad will not. The TPU3A will capture the data of TPU3B ch[0], however, this data will not show on TPU3A ch[0] pad. Same will apply for TPU3A/B ch[1], and when TPU3B is an output.

WORKAROUND:

Connect the external device to the pin of the module that has the output function. Refer to manual dated on or after May 2003.

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CDR_AR_1019

Customer Erratum

RCPU.CDR3LBUSIBUS_17_0

RCPU: Don't execute overflow type before update type MUL/DIV instruction

DESCRIPTION:

When an integer overflow type non multiply or divide instruction (designated by an 'o' in the instruction mnemonic, such as addo) starts to execute before a previously started Condition Register 0 (CR0) update type integer multiply or divide instruction (designated by a '.' in the instruction mnemonic, such as divw.) completes, the CR0[SO] bit may be wrongly updated from the XER[SO] bit earlier changed by the overflow type instruction. For example, instruction sequence "divw. Rx,Ry,Rz , subfo Rt,Ru,Rv" may cause this problem. It does not happen if the overflow type instruction is also a CR0 update type instruction (designated by 'o.' in the instruction mnemonic, such as addo.), or if register dependencies exist.

WORKAROUND:

Do any one of the following: 1) Keep a gap of at least 1 instruction between a CR0 update type integer multiply instruction and an overflow type instruction or a gap of 4 integer or 6 other instructions between a CR0 update integer divide instruction and an overflow type instruction; 2) Use the CR0 update type for both instructions; 3) Run the RCPU in serialized mode; 4) Place a "sync" instruction between the integer multiply/divide instruction and the overflow type instruction; 5) Don't use the update form of integer multiply or divide instructions; or 6) Don't use overflow type integer instructions. (Note: most compiler vendors do not generate the error case.)

CDR_AR_1138

Customer Erratum

RCPU.CDR3LBUSIBUS_17_0

RCPU: Data breakpoint exception may occur even if conditions are not met

DESCRIPTION:

The RCPU may incorrectly take a second data breakpoint exception, if a data breakpoint occurs on a load/store instruction with a load following within five instructions in the RCPU program flow. This extra exception will only be taken if very specific internal bus timing occurs during the instruction sequence and the data breakpoint state remains set after the first data breakpoint exception is taken. In this condition, any load/store instruction executed with breakpoints enabled will cause the second data breakpoint exception. The additional exception sets SRR0 to the effective address of the instruction after the second load/store instruction, but the BAR register remains set to the effective address of the first load/store instruction that met the data breakpoint conditions. If the processor is in a non-recoverable state (MSR[RI] = 0) and breakpoints are not masked (LCTRL2[BRKNOMASK] = 1), the first load/store instruction within the data breakpoint exception handler (usually saving CPU context) will cause the second exception, handler re-entrance and loss of program tracking.

WORKAROUND:

1) Run RCPU in serialized mode. 2) Create conditions for an exception during the data breakpoint exception handler execution after saving SRR0/1 on the stack, for example, use 'SC' instruction inside the handler, or a floating point instruction if the Floating Point Unit is disabled, or an unimplemented instruction. This exception will reset the internal data breakpoint state, eliminating the false data breakpoint exception.

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CDR_AR_907

Customer Information

RCPU.CDR3LBUSIBUS_17_0

RCPU: Issue ISYNC command when entering debug mode

DESCRIPTION:

If the ICTRL[29] bit is set (non-serialized mode) then the RCPU issues two instruction fetch requests into the instruction pipeline after entering debug mode. The debug port and the debug tool may get confused when processing an "mtps DPDR,Rx" instruction. The debug tool loses synchronization with debug port and receives the wrong data for the "Rx" register. The typical case is when the debug tool tries to save scratch registers or read the debug mode cause.

WORKAROUND:

Issue an ISYNC instruction to the debug port prior to any other instructions when the RCPU enters debug mode after running code. Refer to manual dated on or after May 2003.

CDR_AR_440

Customer Information

RCPU.CDR3LBUSIBUS_17_0

RCPU: Execute any IMUL/DIV instruction prior to entering low power modes.

DESCRIPTION:

There is a possibility of higher than desired currents during low power modes. This is caused by a possible contention in the IMUL/DIV control area. This contention may only exist prior to the execution of any IMUL/DIV instruction.

WORKAROUND:

Execute a MULLW instruction prior to entering into any low power mode (anytime after reset, and prior to entering the low power mode). Refer to manual dated on or after May 2003.

CDR_AR_211

Customer Information

RCPU.CDR3LBUSIBUS_17_0

Do not set breakpoint on mtps ICTRL instruction

DESCRIPTION:

When a breakpoint is set on an "mtps ICTRL,Rx" instruction and ICTRL[IIFM] = 1, the result will be unpredictable. The breakpoint may or may not be taken on the instruction and value of the IIFM bit can be either 0 or 1.

WORKAROUND:

Do not put a break point on mtps ICTRL, Rx instruction when ICTRL[IIFM] is set to 1. Refer to manual dated on or after May 2003.

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CDR_AR_214 Customer Information RCPU.CDR3LBUSIBUS_17_0

Only negate interrupts while the MSR[EE] disables interrupts (MSR[EE]=0)

DESCRIPTION:

If the MSR[EE] bit is set and an external interrupt request to the RCPU is negated before the external interrupt vector is issued, the RCPU may become unpredictable until the device is reset. This interrupt event may be generated by software while managing peripheral modules in the MCU, or external devices connected to external interrupt request pins of the MCU or the MCU interrupt controller. This issue may occur when performing USIU operations like masking interrupt requests, clearing interrupt flags, masking or changing interrupt logic in the interrupt controller, or switching on/off enhanced interrupt control if available.

WORKAROUND:

Do not clear an interrupt that is not being serviced by software while MSR[EE]=1. Software should disable interrupts (MSR[EE]=0) in the RCPU before clearing or masking any interrupt source from the USIU, IMB or external pin. For external interrupt request pins, it is recommended that edge triggered interrupts be used. No delay time is required before re-enabling interrupts (MSR[EE]=1). Refer to manual dated on or after May 2003.

CDR_AR_949 Customer Erratum QADC64E.CDR3IMB3_03_0B

QADC64E: Write CCW[EOQ] to 0x3F for the End of Queue

DESCRIPTION:

Using 0x7F as an EOQ (end of queue) causes a conversion of VRL to occur when the EOQ is reached. In single or continuous scan modes, this conversion is underway when the queue wraps back to the first word, and the first conversion is not performed. The result for the conversion of VRL gets written in the result space for the first conversion word. The queue and conversions then proceed on correctly.

WORKAROUND:

Always use 0x3F instead of 0x7F as an EOQ in the CCW for both Legacy and Enhanced modes of QADC64E operation. Refer to an updated Reference Manual dated after January 2003.

CDR_AR_915 Customer Erratum QADC64E.CDR3IMB3_03_0B

QADC64E: Conversion Clock cannot be shared between Master/Slave Modules

DESCRIPTION:

In a multiple QADC64E module configuration it is not possible to operate the modules on synchronous conversion clocks. The conversion clock of a module configured as Master cannot be input to the Slave.

WORKAROUND:

If simultaneous conversions are required, the customer can trigger both QADC64E modules SIMULTANEOUSLY using the external trigger inputs (ETRIG1 or 2), however, the conversions will not be performed SYNCHRONOUSLY. There is no workaround to allow synchronous QADC64E module operation. Do not set EXTCLK of the QADCMCR register to use the conversion clock of a master QADC (don't set to 1). References to this feature are removed in updated Reference Manuals dated after January 2003.

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CDR_AR_1151

Customer Erratum

QSMCM.CDR3IMB3_04_0

SCI: TXD pin reverts to output immediately when SCCxR1[TE] is cleared

DESCRIPTION:

When the Transmitter Enable bit of the SCI Control Register 1 is cleared (SCCxR1[TE]=0), the Transmit Data pin, TXD, reverts immediately to general purpose output mode, and the pin will be driven high or low as determined by the PortQS Data Register, PORTQS. If the transmitter is not idle when SCCxR1[TE] is cleared, any data still being output on the TXD pin will be lost.

WORKAROUND:

Ensure SCCxR1[TE] is only cleared after the Transmit Complete bit of the SCI status Register is set (SCxSR[TC]=1).

CDR_AR_1118

Customer Erratum

READI.CDR3LBUSUBUS_03_0

READI: Program Flow Tracking Error Under Rare Condition

DESCRIPTION:

Under certain conditions, the program trace information output by the READI module may not accurately reflect the actual program flow. This condition requires ALL of the following conditions: 1) Either the BTB or code compression is enabled. 2) A double branch instruction sequence must occur where: the first branch is indirect and its condition is already determined or is non-conditional, the second branch is conditional and is miss-predicted and then corrected due to a long (execution time) instruction. And 3) the BBC must be held off the U-bus so that U-bus show cycle addresses are delayed.

WORKAROUND:

Either disable code compression and the BTB, or accept erroneous trace reconstruction under this rare condition.

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CDR_AR_846 Customer Information READI.CDR3LBUSUBUS_03_0

READI: Synchronize the MCKI input clock to the MCKO output clock.

DESCRIPTION:

The READI module may not properly receive input messages if the input clock is not synchronous with the output clock.

WORKAROUND:

Synchronize the MCKI input clock to the MCKO output clock. Refer to manual dated on or after May 2003.

CDR_AR_698 Customer Information READI.CDR3LBUSUBUS_03_0

READI Input message requires 2 MCKI idle after READI Enabled.

DESCRIPTION:

If an input message is sent to the READI immediately after deassertion of RSTI_B (enabling READI) the READI may not recognize the start of the message and will ignore it. This behavior could cause the tool to get out of sync with the READI.

WORKAROUND:

Do not send an input message until at least 2 MCKI after READI is enabled, or better, until the DID message is received from the READI. Refer to manual dated on or after May 2003.

CDR_AR_1096 Customer Information READI.CDR3LBUSUBUS_03_0

READI: New features to enhance Nexus debug

DESCRIPTION:

New features have been added to the READI to provide enhanced Nexus debug capabilities. (1) The Nexus message queue has been increased from 16 locations to 32 locations. (2) A new register READI_MC has been added with bits to control the following: Program Trace Sync Mode (PTSM) which optionally adds an I-CNT packet to message, Queue Flush Mode (QFM) that allows the user to control the message buffer action when a message overflow occurs, and Program Trace Mode (PTM) that allows Nexus trace with an ICTRL[ISCT_SER]=0x6. (3) Nexus Public Messages have been added or modified. (4) The manufacturer ID in the READI DID has been corrected to 0xE. (5) A change was made to the data trace message to allow tools to differentiate between 8-bit data reads and 16 bit data reads.

WORKAROUND:

Tools must be updated to allow use of the new features. Consult updated Reference Manuals dated after November 2002.

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CDR_AR_1144

Customer Erratum

TOUCAN.CDR3IMB3_05_1A

TouCAN: Transmit buffers may freeze or indicate missing frame

DESCRIPTION: If a received frame is serviced during reception of a second frame identified for the same MB (message buffer) and a new Tx frame is also initiated during this time, the Tx MB can become frozen and will not transmit while the bus is idle. The MB remains frozen until a new frame appears on the bus. If the new frame is a received frame, the frozen MB is released and will arbitrate for external transmission. If the new frame is a transmitted frame from another Tx MB, the frozen MB changes its C/S (control status word) and IFLAG to indicate that transmission has occurred, although no frame was actually transmitted. The frozen MB occurs if lock, unlock and initiate Tx events all occur at specific times during reception of two frames. The timing of the lock event affects the timing window of the unlock event as follows: Situation A) Rx MB is locked during the second frame. A frozen Tx MB occurs if: 1) Both of these events occur in either a-then-b or b-then-a order: a) A new transmission is initiated by writing its C/S between CRC6 (sixth bit of CRC field) and EOF7 (seventh bit of end of frame) of the second frame. b) The Rx MB is locked by reading its C/S after EOF6 of first frame and before EOF6 of second frame. 2) The Rx MB is unlocked between EOF7 and intermission at end of the second frame. Notice in this situation that if the lock/unlock combination happens close together, the lock must have been just before EOF6 of the second frame, and therefore the system is very close to having an overrun condition due to delayed handling of received frames. Situation B) Rx MB was locked before EOF6 of the first frame; in other words, before its IFLAG is set. This is a less likely situation but provides a larger window for the unlock event. A frozen Tx MB occurs if: 1) The Rx MB is locked by reading its C/S word before EOF6 of the first frame. 2) Both of these events occur in either a-then-b or b-then-a order: a) A new transmission is initiated by writing its C/S word sometime between CRC6 and EOF7 of the second frame. b) The Rx MB is unlocked between CRC6 and intermission at end of the second frame. Notice in this situation that if the unlock event occurs after EOF6, the first frame would be lost and the second frame would be moved to the Rx MB due to the delayed handling of received frames. Situation C) Rx unlocked during bus idle. A frozen/missing Tx occurs if: 1) An Rx MB is locked before EOF6 of an incoming frame with matching ID and remains locked at least until intermission. This situation would usually occur only if the received frame was serviced after reception of a second frame. 2) An internal arbitration period is triggered by writing a C/S field of an MB. 3) The locked Rx MB is unlocked within two internal arbitration periods (defined below) before or after step 2). 4) 0xC is written to the C/S of a Tx MB within these same two arbitration periods. This step is optional if 0xC was written in step 2) above. Two internal arbitration periods are calculated as $(2 * \text{number of MBs}) + 16$ IMB clocks. Additional Notes: 1) The received frames can be transmitted from the same node, but they must be received into an Rx MB. 2) When the frozen Tx MB's IFLAG becomes set, an interrupt will occur if enabled. 3) The timestamp of the missing Tx will be set to the same timestamp value as the last reception before it was frozen. 4) If the user software locks the Rx MB before a frame is received, situation A can occur with a single received frame. 5) The issue does not occur if there were any additional pending Tx MBs before CRC6. 6) If multiple Tx MBs are initiated within the CRC6/EOF7 window (situation A and B) or two internal arbitration windows (situation C), they all become frozen.

WORKAROUND:

If received frames can be handled (lock/unlocked) before EOF6 of the next frame, situations A and C are avoided. If they are handled before CRC6, or lock times are below 23 CAN bit times, situation B is avoided. If these conditions cannot be guaranteed, situation A and B are avoided by inserting a delay of at least 28 CAN

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bit times between initiating a transmission and unlocking an Rx MB, and vice versa. Typically a system would use a mechanism to selectively add the necessary delay. For example, software might use a global variable to record an external timer value (the TouCAN timer can't be used as that would unlock) when initiating a new Tx or unlocking an Rx, and then add the required delay before performing second action. Situation C can be avoided by inserting a delay of at least two internal arbitration periods between writing 0xC and unlocking the locked Rx MB.

CDR_AR_1045	Customer Information	TOUCAN.CDR3IMB3_05_1A
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CAN: Bus Off recovery not ISO compliant

DESCRIPTION:

The Bus Off recovery is not ISO compliant on the FlexCAN and TouCAN modules. The ISO specification indicates that the CAN node should remain inactive until user intervention restarts it. The FlexCAN and TouCAN modules both include an automatic recovery mechanism for the Bus Off condition.

WORKAROUND:

The Bus Off condition interrupt should be enabled and an interrupt service routine implemented to disable the CAN. The user's software should then determine when the CAN should be re-activated.

CDR_AR_1142	Customer Information	TOUCAN.CDR3IMB3_05_1A
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TouCAN: Writing to an active receive MB may corrupt MB contents

DESCRIPTION:

Deactivating a TouCAN receive message buffer (MB) may cause corruption of another active receive MB, including the ID field, if the following sequence occurs. 1) A receive MB is locked via reading the Control/Status word, and has a pending message in the temporary receive serial message buffer (SMB). 2) A second frame is received that matches a second receive MB, and is queued in the second SMB. 3) The first MB is unlocked during the time between the CRC field and the 6th bit of end of frame (EOF) of the second frame. 4) The second MB is deactivated within 20 IMB clock cycles of the 6th bit of EOF, resulting in corruption of the first MB.

WORKAROUND:

Do not write to the Control/Status word after initializing a receive MB. If a write (deactivation) is required to the Control/Status field of an active receive MB, either FREEZE the TouCAN module or insert a delay of at least 27 CAN bit times plus 21 IMB clock cycles between unlocking one MB and deactivating another MB. This will avoid MB corruption; however frames may still be lost.

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CDR_AR_1152 Customer Erratum USIU.CDR3UBUS_12_0
USIU: PORESET must always be asserted before the 2.6V supplies reach 0.5V

DESCRIPTION:

When exiting low power modes where the 2.6V supplies (VDD, QVDDL, NVDDL and VDDSYN) are off (Power-down and SRAM Standby modes), correct operation cannot be guaranteed if the 2.6V supplies are above 0.5V before PORESET is asserted. For example, the CALRAM or flash contents may be corrupted.

WORKAROUND: Ensure PORESET is asserted before ramping the 2.6V supplies above 0.5V in any power-up sequence.

CDR_AR_867 Customer Erratum USIU.CDR3UBUS_12_0

USIU: Do not operate USIU burst on a burst-inhibited memory region

DESCRIPTION:

If the SIUMCR[BURST_EN] is set and a burst-inhibited code region (memory) is accessed (either by asserting bi_b pin or setting the BI bit in the corresponding ORx memory controller register) then the CPU will not execute code properly.

WORKAROUND:

Do not set the SIUMCR[BURST_EN] while trying to run code from an external non-burstable memory.

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CDR_AR_1154

Customer Erratum

USIU.CDR3UBUS_12_0

SIU: RTSEC register not documented; May affect the initial increment of the RTC

DESCRIPTION:

The Reference Manuals have an incomplete statement in the description of the RealTime Clock register (RTC). In addition, the reserved Real-Time Clock Predivider Register (RTSEC) is not documented and may affect the initial increment of the RTC (seconds) counter. In the Reference Manual, the statement "A write to the RTC resets the seconds timer to zero." is incorrectly worded. A better statement that fully describes the this action would be: "A write of 0 to the RTC must be performed to reset the RTC (seconds) timer to zero." The RTSEC register is the predivider to the RTC (seconds) timer. The RTC, the RTSEC, and the Real Time Clock Alarm (RTCAL) registers, as well as the Real-Time Clock Enable [RTE] and the RealTime Clock Source [4M] bits of the Real Time Clock Control and Status Register (RTCSC), are not affected by any reset (unchanged) and power up in a random state. This will cause the initial increment of the RTC to be between one system clock and 26143 PITRTRCLK clocks. All of these bits and registers must be initialized the first time they are used or if known start points are required. RTSEC is implemented as an 18-bit counter that is left justified in a 32-bit word at address 0x2F_C228. The RTC Alarm itself is always disabled by reset, but RTCAL should be initialized to the desired alarm time, if required, before the Alarm Interrupt Enable (ALE) in the RTCSC is enabled (RTCSC[ALE]=0b1).

WORKAROUND:

To properly initialize the RTC timer to a completely known state with the most accurate startup, the following sequence must be used. 1) The Real-Time Clock Enable [RTE] and the Real-Time Clock Source [4M] bits must be configured in the Real-Time Clock Control and Status Register (RTCSC) after any true power on reset (if KAPWR is powered up) prior use of the RTC. The bits must be initialized since they are not affected by any reset and can be in a random state after the power up. For the most accuracy in the start value of the RTC, RTE should be cleared during this step. For the most accuracy in the start value of the RTC, RTE should be cleared during this step. 2) In order to guarantee that the first increment of the RTC register occurs in approximately 1 second (depending on whether a 4 MHz or 20 MHz crystal is being used), the reserved register RTSEC must also be initialized by writing either 0x0F42_4000 (if using a 4 MHz crystal) or 0x4C4B_4000 (if using a 20 MHz crystal). Alternately, RTSEC could be written to 0 and RTSEC will be updated automatically to these values, but will then immediately (within one PITRTRCLK clock) increment the RTC when the RTC is enabled. 3) If a known starting point is desired (like 0), a value must be written to the Real-Time Clock register (RTC). 4) RTE bit should be then be set in the RTCSC register to enable RTC operation. Note that the RTCSC, the RTC, and the RTSEC registers are locked following all resets and must be unlocked. The RTSEC can be unlocked by writing 0x55CC_AA33 to address 0x2F_C328.

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CDR_AR_1113	Customer Information	USIU.CDR3UBUS_12_0
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USIU: Ensure HRESET/SRESET negation time is longer than 3 CLKOUT periods

DESCRIPTION:

If either HRESET or SRESET are externally re-asserted after a negation time of less than 3 CLKOUT clocks, and after an initial assertion of more than 512 CLKOUT periods, the MCU will remain in that reset until PORESET is applied. In the case of SRESET being the cause, then HRESET can also clear the locked condition. In the case of HRESET being the cause then SRESET will be held asserted internally by the MCU. The SWT (Software Watchdog Timer) will not clear the locked condition.

WORKAROUND:

Do not re-assert HRESET/SRESET within 3 CLKOUT periods of the previous HRESET/SRESET negation; Or apply PORESET.

CDR_AR_869	Customer Information	USIU.CDR3UBUS_12_0
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USIU: Do not enable BRx[SST] with SCCR[EBDF]>0

DESCRIPTION:

When EBDF>0 an external burst access with short setup timing will corrupt any USIU register load/store

WORKAROUND:

Do not enable BRx[SST] while EBDF>0. Refer to manual dated on or after May 2003.

CDR_AR_895	Customer Information	USIU.CDR3UBUS_12_0
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USIU: Do not assert TEA pin on fetch while SIUMCR[BURST_EN] bit set.

DESCRIPTION:

If USIU burst is enabled (SIUMCR[BURST_EN]) a transfer error indication (internal by Bus Monitor, Chip Select Region access attribute mismatch, or external by TEA signal) may cause the chip to stop executing until reset. In some cases the address read from the SRR0 register in Machine Check Exception handler may not precisely indicate the exact faulty bus address causing the exception. The RCPU will pre-fetch code from the memory address after the last address of the Chip Select region. When the pre-fetch causes a Transfer Error Acknowledge, either by the Bus Monitor or by a Supervisor/User attribute mismatch in the Memory Controller Region, the RCPU will hang up even if the pre-fetch was unnecessary for code execution.

WORKAROUND:

1. Do not assert TEA on the external bus for instruction fetch while the SIUMCR[BURST_EN] bit is set. 2. Do not place code at the 8 last words of a memory controller region while the SIUMCR[BURST_EN] bit is set. Refer to manual dated on or after May 2003.

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CDR_AR_1120

Customer Information

USIU.CDR3UBUS_12_0

USIU: Interrupt Controller may generate vector 0x0 or has no request indication

DESCRIPTION:

When software masks interrupt requests, clears interrupt flags, stops or disables a module, or masks or changes interrupt logic in the UIMB or the USIU interrupt controller while MSR[EE] = 1, the interrupt request may disappear during or after the RCPU has acknowledged the external interrupt exception. It may also occur after re-enabling interrupts in the RCPU. This may cause the following: 1. When external interrupt relocation is enabled, the BBC may issue a vector offset of 0x0. 2. The SIPEND registers will not contain set bits, and if the service routine polls for a set bit it may hang. 3. The SIVEC register may contain a value of zero which could cause software to branch to an unmapped location.

WORKAROUND:

Follow the workarounds in AR_214, however, note that a time delay is required prior to re-enabling interrupts. Before clearing an interrupt related register, ensure that MSR[EE] = 0. Expect a vector offset of 0x0 if an interrupt is cleared or disabled while MSR[EE] = 1. This vector should be handled as if no interrupt has occurred, i.e. perform an RFI. After clearing an interrupt source, sufficient time must occur before re-enabling interrupts in the RCPU. This time should take longer than the time needed for a load of the same register that was just cleared. If unsure, include this load instruction before the instruction that re-enables interrupts in the RCPU. Refer to manual dated on or after May 2003.

CDR_AR_1137

Customer Information

USIU.CDR3UBUS_12_0

USIU: RSR[LLRS] can be set even though no loss of lock reset has occurred

DESCRIPTION:

If the Loss of Lock Reset Enable bit in the PLPRCR register is set when the PLL Multiplication or Division Factor value is changed (PLPRCR[MF] or PLPRCR[DIVF]), the Loss of Lock Reset Status bit in the RSR register will be set (RSR[LLRS] = 1), even though a reset does not occur.

WORKAROUND:

Enable PLPRCR[LOLRE] after setting PLPRCR[MF] and PLPRCR[DIVF] values, or if PLPRCR[LOLRE] is already enabled, clear RSR[LLRS] after changing the value of PLPRCR[MF] or PLPRCR[DIVF].

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CDR_AR_1155

Customer Information

USIU.CDR3UBUS_12_0

SIU: TEA for external access must be negated within 1 system bus clock

DESCRIPTION:

When accessing external memory and the SIU bus monitor terminates the cycle with a Transfer Error Acknowledge (TEA), the SIU may produce unexpected results on subsequent accesses to the SIU address space, including SIU internal registers reads. This condition occurs when the TEA signal (pin) is not negated within 1 system clock of the time that the MCU stops asserting the TEA signal. While TEA is asserted by the MCU, it must be negated by the required external pull-up resistor. While the TEA negation requirement (1 clock) is documented in the Reference Manual, it may not be obvious that internally terminated accesses of an external memory space require the use of the external pull-up resistor. The value of the resistor should be small enough to pull the TEA line up to VIH level faster than one system clock and depends on the TEA line/board wire capacitance. Circuitry inside the MCU generates an actively driven TEA for accesses to internal non-existent memory spaces and does not rely on the external pull-up resistor to negate the cycle.

WORKAROUND:

Insure that the external pull-up resistor on the TEA pin is sufficient to negate TEA within one system clock. A value of 1K is recommended.